

thin film deposition. The substrate is kept above the burner by a holder. The precursor of TiO₂, titanium tetraisopropoxide (TTIP, Ti(C₃H₇O)₄), is contained in a bubbler, and the mass flow rate of TTIP is controlled by the N₂ carrier gas flow rate to the bubbler. TTIP vapor was carried through the central tube to the burner tip. To maintain the gas flow rate to the central tube constant, an auxiliary N₂ gas flow was introduced to the central tube. O₂ of 1 L/min and 200 ml/min methane as fuel were supplied to the second and the third concentric tubes, respectively. The ambient N₂ gas of 250 ml/min was provided through the fourth concentric tube. The combustion of CH₄ takes place just after the burner tip. TTIP decompose to form TiO₂ particles at high temperature in the oxy-CH₄ flame. By thermophoresis and diffusion, TiO₂ particles finally deposit on the silicon wafer substrate to form thin film. In our study, first, TiO₂ thin films were prepared by maintaining total flow rate of N₂ through the central tube at 400 ml/min while varying the carrier gas flow rate to bubbler from 100 to 300 ml/min, which means the gas residence time was kept constant. Second, we changed the total carrier gas flow rate of N₂ through the central tube from 300 to 500 ml/min while keeping the carrier gas flow rate constant at 200 ml/min, which means the mass flow rate of TTIP was kept constant. We also investigated the effect of the distance between substrate and burner (10 cm and 7 cm) on the thickness distribution of deposited thin film and the crystal phase. The bubbler and precursor delivery tubes were heated to 80 °C to prevent TTIP condensation.

The TiO₂ thin films were deposited on silicon wafer. By scraping the wafer with a blade, TiO₂ particles were collected. The specific surface area (SSA, m²/g) was measured by using the Brunauer-Emmett-Teller (BET) method (ASAP 2020, Micromeritics). The TiO₂ samples were degassed at 200 °C for 10 hours to remove gases and moisture from the surface by flowing N₂ for BET measurement. Assuming all particles to be monodisperse spherical particles, the BET-equivalent particle diameter, d_{BET} (nm), was calculated as follows [14]:

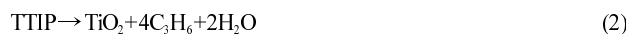
$$d_{BET} = \frac{6}{(\rho_p \times SSA)} \quad (1)$$

where ρ_p is the particles density (g/m³), and we considered ρ_p as 4.0 g/m³. The secondary particle size of TiO₂ was characterized by electrophoretic light scattering (ELS). Before analysis by ELS, samples were dispersed in deionized water with sonication for 1 hour at room temperature. The ELS analysis was performed with ELS-8000 (photal Otsuka Electronisc). The crystal phase was determined by X-ray diffraction (XRD). The XRD measurements were operated by using PW3040/60 X'Pert PRO (PANalytical) instrument using Ni filtered Cu K α radiation (wavelength=1.54 Å). 2 θ scan ranges from 20° to 80° and scanning step size of 0.02° were used. To measure the thickness of thin films, we fixed the glass slide to the wafer by binder clip before deposition. TiO₂ thin films were deposited on the glass slide and also on the wafer. Then, the glass slide with TiO₂ thin film was cut to several pieces at even intervals to measure the distribution of film thickness in cross-section by scanning electron microscopy (SEM, S-4300, Hitachi).

RESULTS AND DISCUSSION

Methane combustion reaction took place at the burner tip and

provided energy for TTIP decomposition. When the N₂ gas carried TTIP vapor to the burner tip, it was immediately decomposed to form tiny TiO₂ monomer particle in the oxy-CH₄ flame. The decomposition reaction of TTIP is shown as follows:



with a reaction rate constant $k=3.96 \times 10^5 \exp(-8479.7/T)$ for $T=500-670$ K [15]. Once the TTIP decomposition reaction occurs, TiO₂ monomers are generated. They collide with each other and coalesce to form single larger spherical particles upon passing the high flame temperature region where the coalescence rate might be faster than the collision rate. Later on, in the downstream region, where the flame temperature cools down, the coalescence rate becomes slower than the collision rate of particles, so the particles are covalently bonded with each other by sintering necks and become the aggregates. Further downstream, the aggregates collide with other particles to form the agglomerates which can be easily broken down into the aggregates because the temperature there is too low for sintering, and they hold each other by van der Waals forces rather than chemical interactions. The deagglomeration process can be accomplished by dispersing them in proper solutions and appropriate external forces such as mechanical stirring or sonication [16].

It is well known that photocatalytic activity of TiO₂ is also influenced by crystal structure, which is strongly affected by flame temperature. We prepared TiO₂ thin films for different ratios of CH₄/O₂ flow rates. As CH₄ flow rate decreases from 300 to 200 ml/min, it can be seen from Figs. 2(a) and (b) that the flame height becomes shorter, and the flame temperature correspondingly decreases. XRD patterns in Fig. 2(c) show that, for CH₄ flow rate of 200 ml/min, the prepared TiO₂ films have the single crystal anatase phase. However, for the case of 300 ml/min, the flame temperature increases and the rutile phase appears. Thus, we can see that by changing the

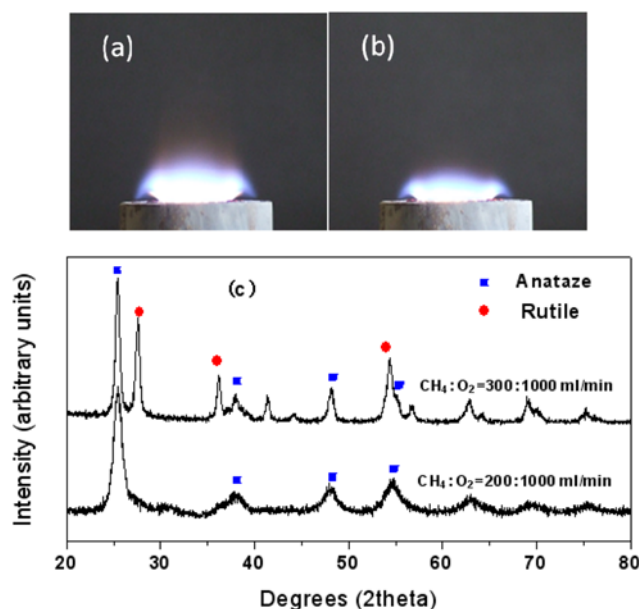


Fig. 2. Photographs of oxy-methane flame at (a) CH₄ : O₂ = 300 : 1,000 ml/min, (b) CH₄ : O₂ = 200 : 1,000 ml/min; (c) X-ray diffraction patterns of TiO₂ nanoparticles collected from silicon wafer substrates for various CH₄ flow rates.

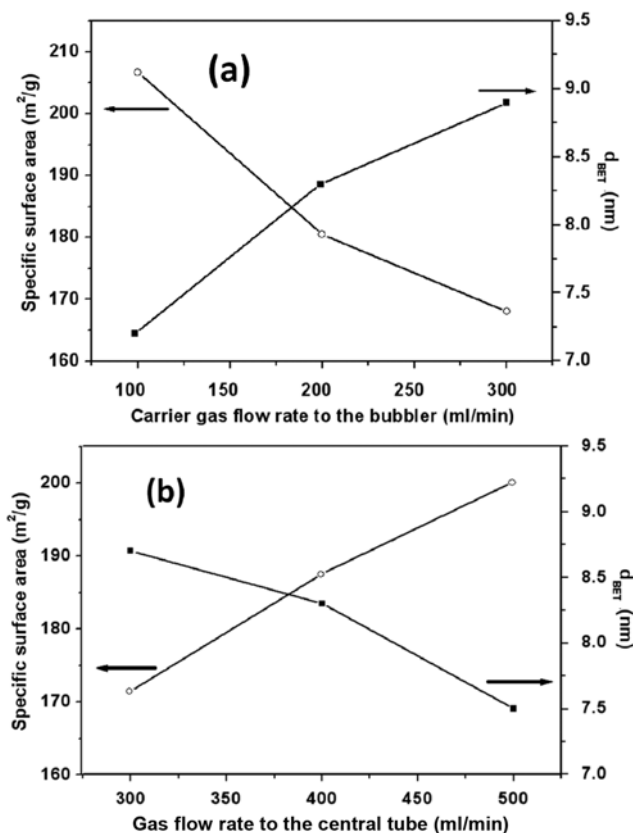


Fig. 3. Specific surface area and BET equivalent diameters (d_{BET}) of particles collected from silicon wafer substrates (a) for different N_2 carrier gas flow rate to the bubbler; (b) for different N_2 gas flow rate to the central tube ($CH_4 : O_2 = 200 : 1,000$ ml/min, deposition time=30 min, deposition height=10 cm above the burner).

ratio of CH_4/O_2 flow rates we can control the amounts of anatase and rutile crystal structures.

By BET method, the specific surface area of TiO_2 particles was measured. We calculated the diameters of particles based on Eq. (1). In Fig. 3(a), as the N_2 carrier gas flow rate to bubbler increases, the specific surface area of particles decreases, which means that the primary particle size increases. By increasing N_2 carrier gas flow rate to bubbler, initial TTIP concentration becomes higher and more TiO_2 monomers are formed in the high temperature zone of flame. The increased number of monomers resulted in shorter collision time between particles [17] and also in larger particle size due to faster coagulation and sintering. However, as total N_2 gas flow rate to the central tube increases, the specific surface area increases, and the primary particle size decreases correspondingly as shown in Fig. 3(b). By increasing total gas flow rate to the central tube, the residence time of particles for coagulation at high temperature decreases and the resultant particle size decreases.

The surface area is also an important characteristic of photocatalytic TiO_2 particles. The specific surface area of the commercial TiO_2 Degussa P25 is $50.0 \text{ m}^2/\text{g}$ [5]. The TiO_2 particles we prepared have the specific surface area larger than that of Degussa P25 by more than three times. Fig. 4 shows the cross-sectional SEM images of TiO_2 thin films. The morphologies of thin films are all similar in

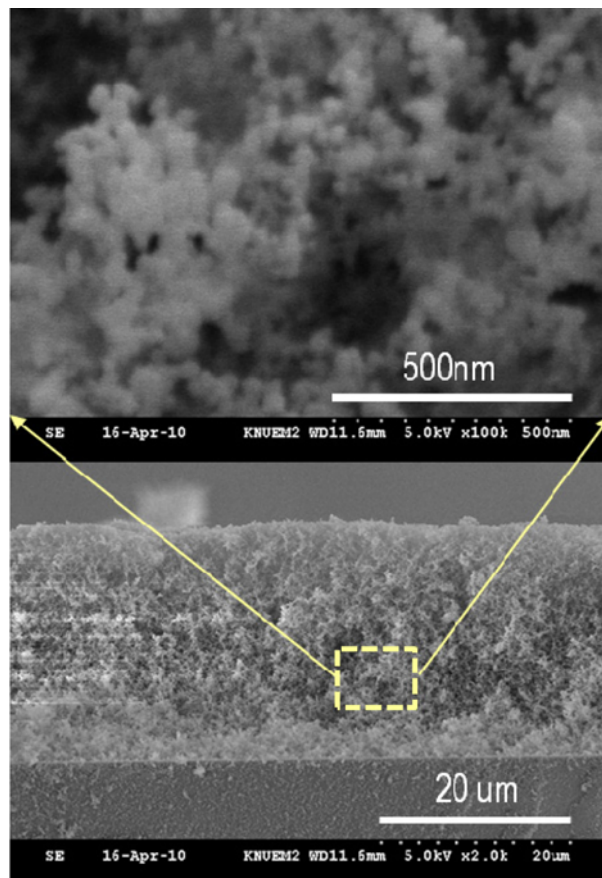


Fig. 4. Cross-sectional SEM images of TiO_2 thin film ($CH_4 : O_2 = 200 : 1,000$ ml/min, carrier gas N_2 flow rate to the bubbler: 200 ml/min, N_2 gas flow rate to the central tube: 400 ml/min, deposition time=30 min, deposition height=10 cm above the burner).

our experimental conditions. From this result, we can see that TiO_2 thin film has high porosity, which also leads to high surface area for photocatalysts.

To measure the secondary particle size (average aggregate size), the samples were dispersed in the deionized water with sonication for 1 hour at room temperature. By sonication, the agglomerated particles can be broken down into the aggregates which cannot be broken down into individual primary particle easily because of the strong covalent bond between primary particles. Right after sonication, the secondary particle sizes were analyzed by ELS. Fig. 5(a) and (b) show the change of secondary particle size for various N_2 carrier gas flow rates to bubbler and also for various total gas flow rates of N_2 through the central tube, respectively. We can see that the secondary particle size increases with increasing N_2 carrier gas flow rate to bubbler, but decreases with increasing total gas flow rate of N_2 through the central tube. A higher N_2 carrier gas flow rate to bubbler leads to a higher initial TTIP concentration; thus, more particles generated in the high temperature region. Therefore, the bigger aggregates are formed by faster coagulation and sintering. By increasing total gas flow rate of N_2 to the central tube, the residence time of aggregates in the high temperature flame region decreases, and the secondary particle size decreases correspondingly.

We prepared TiO_2 thin films with different deposition height (7 cm

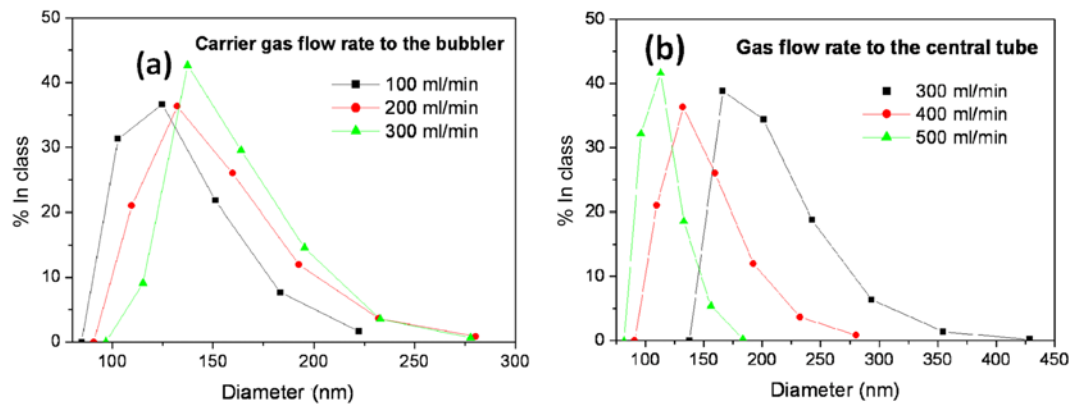


Fig. 5. Secondary particle size distributions by ELS based on number of TiO₂ particles prepared by changing (a) carrier gas N₂ flow rate to the bubbler from 100 to 300 ml/min, (b) total N₂ gas flow rate through the central tube from 300 to 500 ml/min (CH₄ : O₂=200 : 1,000 ml/min, deposition time=30 min, deposition height=10 cm above the burner).

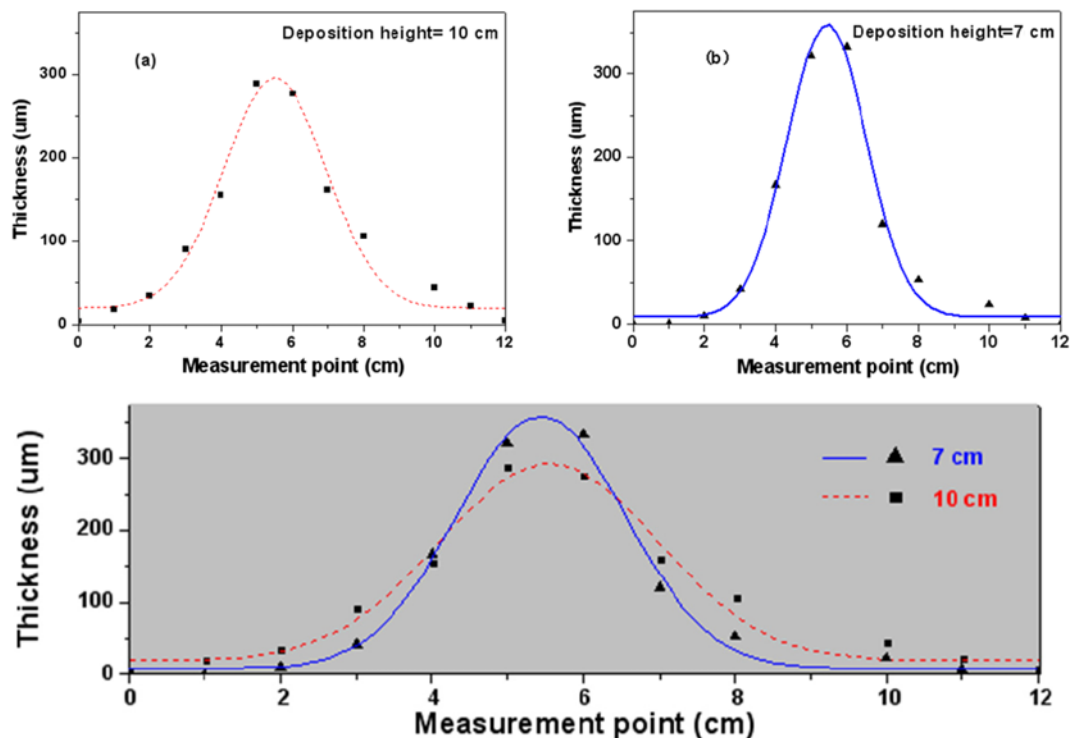


Fig. 6. The distribution of film thickness deposited on substrate for deposition height of (a) 10 cm, (b) 7 cm above the burner (carrier gas N₂ flow rate to the bubbler: 200 ml/min, CH₄ : O₂=200 : 1,000 ml/min, deposition time=30 min, N₂ gas flow rate to the central tube: 400 ml/min).

and 10 cm) to examine the distribution of film thickness on substrate. The thickness was measured through the cross-sectional SEM image. From Fig. 6, we can see that the shorter the distance between substrate and burner is, the smaller deposition area on substrate is, but the thicker the film thickness is in the central region of flame. The generated particles are transported by the convective flow and thermophoretic force as well as diffusion of particles. As the deposition height increases, more particles are diffused in the radial direction, which leads to the larger deposition area. The shorter distance between substrate and burner results in steeper gas temperature gradient and the thermophoretic deposition rate of TiO₂ particles onto the substrate increases, so the thickness of thin film in the central

region prepared with 7 cm deposition height is thicker than that prepared with 10 cm deposition height.

CONCLUSIONS

Nanostructured TiO₂ thin films were prepared by AFD process for various process conditions of different gases flow rate, TTIP vapor concentration and deposition height. The prepared TiO₂ particles have a specific surface area three-times larger than that of commercial Degussa P25. Crystallite structure of TiO₂ particles could be controlled by changing the ratio of CH₄/O₂ flow rates. We prepared TiO₂ thin films with single anatase phase by keeping the CH₄ and

O₂ flow rates of 200 and 1,000 ml/min, respectively. As N₂ carrier gas flow rate to bubbler increases, the primary and secondary particle sizes increase. However, the primary and secondary particle sizes decrease with increasing total gas flow rate of N₂ through the central tube. We also examined the dependence of thin film thickness and deposition area on the distance between substrate and burner tip. The shorter the deposition height is, the smaller deposition area is, but the thin film is thicker in the central region. This study provides necessary information for our further studies to make uniform coating on large surface area substrate using AFD process.

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